NEC

MOS INTEGRATED CIRCUIT

μPD421805

1 M-BIT DYNAMIC RAM
128K-WORD BY 8-BIT, HYPER PAGE MODE (EDO)

Description

The μPD421805 is a 131,072 words by 8 bits CMOS dynamic RAM with optional hyper page mode (EDO).

Hyper page mode (EDO) is a kind of the page mode and is useful for the read operation.

The μPD421805 is packaged in 28-pin plastic TSOP (II) and 28-pin plastic SOJ.

Features

- Hyper page mode (EDO)
- 131,072 words by 8 bits organization
- Single +5.0 V ±10 % power supply
- $\overline{CAS}$ before $\overline{RAS}$ refresh, $\overline{RAS}$ only refresh, Hidden refresh
- 512 refresh cycles/8 ms
- Fast access and cycle time

★

Part number	Power consumption		Access time (MAX.)	R/W cycle time (MIN.)	Hyper page mode (EDO) cycle time (MIN.)
	Active (MAX.)	Standby (MAX.)			
μPD421805-25	605 mW	5.5 mW (CMOS level input)	60 ns	109 ns	25 ns
μPD421805-30	550 mW		70 ns	124 ns	30 ns
μPD421805-35					35 ns

The information in this document is subject to change without notice.

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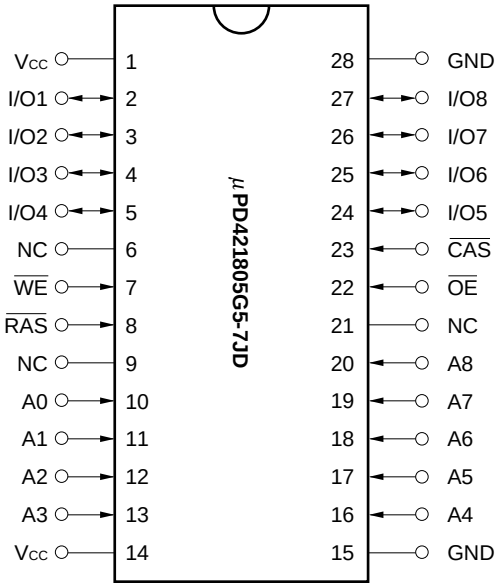
The mark ★ shows major revised points.

★ Ordering Information

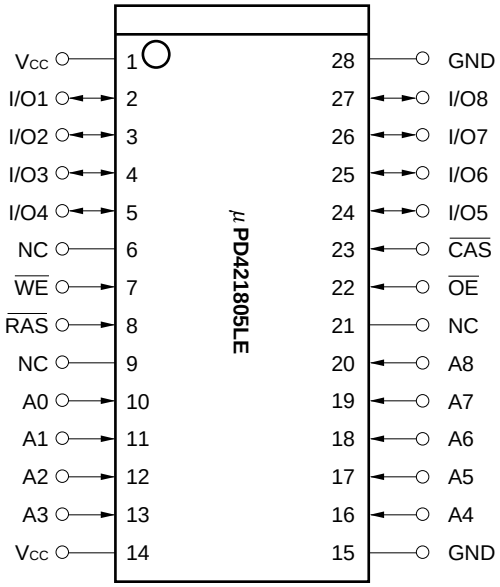
Part number	Access time (MAX.)	Hyper page mode (EDO) cycle time (MIN.)	Package	Refresh
μPD421805G5-25-7JD	60 ns	25 ns	28-pin plastic TSOP (II) (400 mil)	$\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD421805G5-30-7JD	70 ns	30 ns		
μPD421805G5-35-7JD	70 ns	35 ns		
μPD421805LE-25	60 ns	25 ns	28-pin plastic SOJ (400 mil)	
μPD421805LE-30	70 ns	30 ns		
μPD421805LE-35	70 ns	35 ns		

Pin Configurations (Marking Side)

28-pin Plastic TSOP (II) (400 mil)

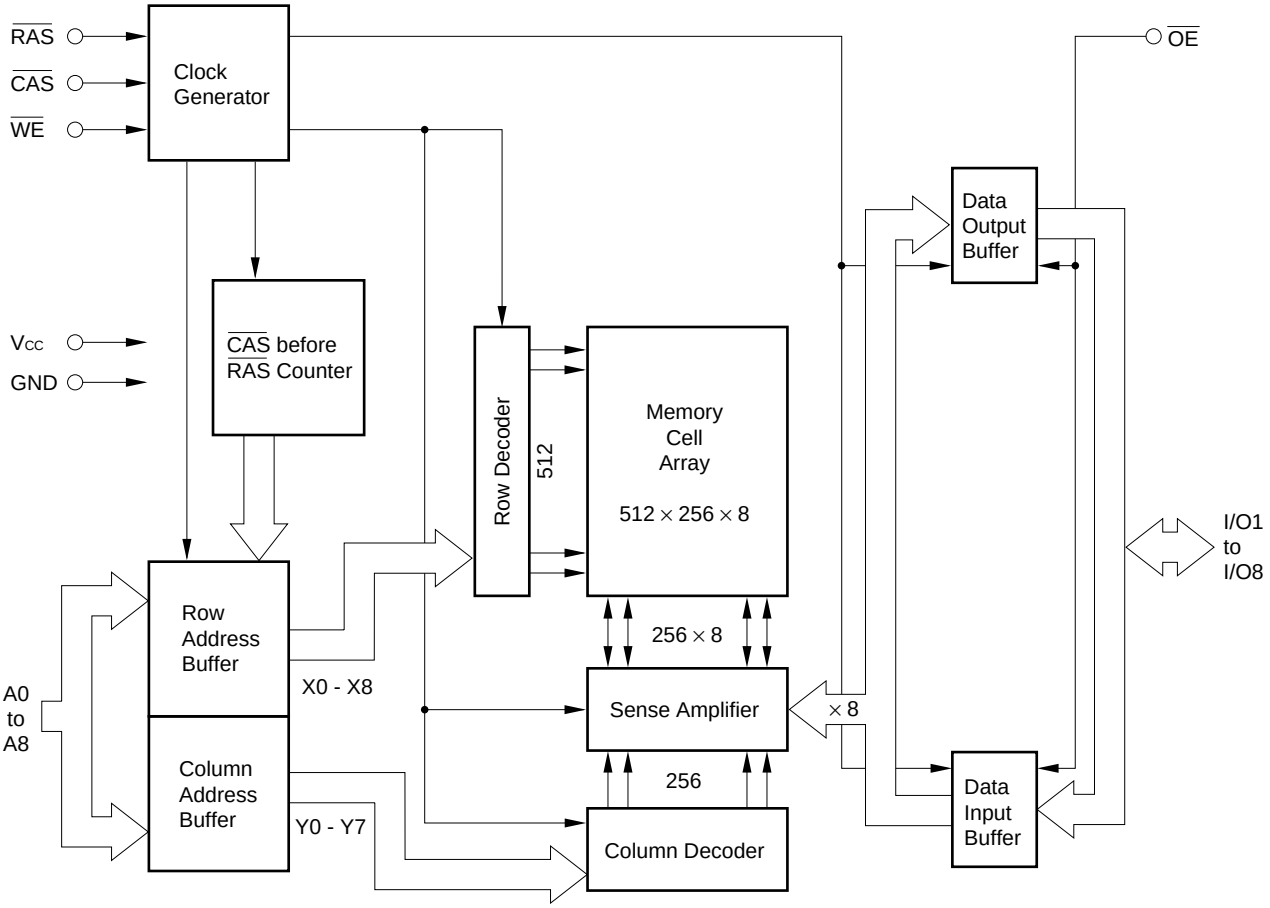


28-pin Plastic SOJ (400 mil)



A0 to A8 : Address Inputs
I/O1 to I/O8: Data Inputs/Outputs
$\overline{RAS}$: Row Address Strobe
$\overline{CAS}$: Column Address Strobe
$\overline{WE}$: Write Enable
$\overline{OE}$: Output Enable
V_{CC} : Power Supply
GND : Ground
NC : No Connection

Block Diagram



Input/Output Pin Functions

The μPD421805 has input pins $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$, A0 to A8 and input/output pins I/O1 to I/O8.

Pin name	Input/Output	Function
$\overline{RAS}$ (Row address strobe)	Input	$\overline{RAS}$ activates the sense amplifier by latching a row address and selecting a corresponding word line. It refreshes memory cell array of one line selected by the row address. It also selects the following function. • $\overline{CAS}$ before $\overline{RAS}$ refresh
$\overline{CAS}$ (Column address strobe)	Input	$\overline{CAS}$ activates data input/output circuit by latching column address and selecting a digit line connected with the sense amplifier.
A0 to A8 (Address inputs)	Input	Address bus. Input total 17-bit of address signal, upper 9-bit and lower 8-bit in sequence (address multiplex method). Therefore, one word is selected from 131,072-word by 8-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{RAS}$. Then, switch the address bus to column address and activate $\overline{CAS}$. Each address is taken into the device when $\overline{RAS}$ and $\overline{CAS}$ are activated. Therefore, the address input setup time (t_{ASR}, t_{ASC}) and hold time (t_{RAH}, t_{CAH}) are specified for the activation of $\overline{RAS}$ and $\overline{CAS}$.
$\overline{WE}$ (Write enable)	Input	Write control signal. Write operation is executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{WE}$.
$\overline{OE}$ (Output enable)	Input	Read control signal. Read operation can be executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{OE}$. If $\overline{WE}$ is activated during read operation, $\overline{OE}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O8 (Data inputs/outputs)	Input/Output	8-bit data bus. I/O1 to I/O8 are used to input/output data.

Hyper Page Mode (EDO)

The hyper page mode (EDO) is a kind of page mode with enhanced features. The two major features of the hyper page mode (EDO) are as follows.

1. Data output time is extended.

In the hyper page mode (EDO), the output data is held to the next $\overline{CAS}$ cycle's falling edge, instead of the rising edge. For this reason, valid data output time in the hyper page mode (EDO) is extended compared with the fast page mode (= data extend function). In the fast page mode, the data output time becomes shorter as the $\overline{CAS}$ cycle time becomes shorter. Therefore, in the hyper page mode (EDO), the timing margin in read cycle is larger than that of the fast page mode even if the $\overline{CAS}$ cycle time becomes shorter.

2. The $\overline{CAS}$ cycle time in the hyper page mode (EDO) is shorter than that in the fast page mode.

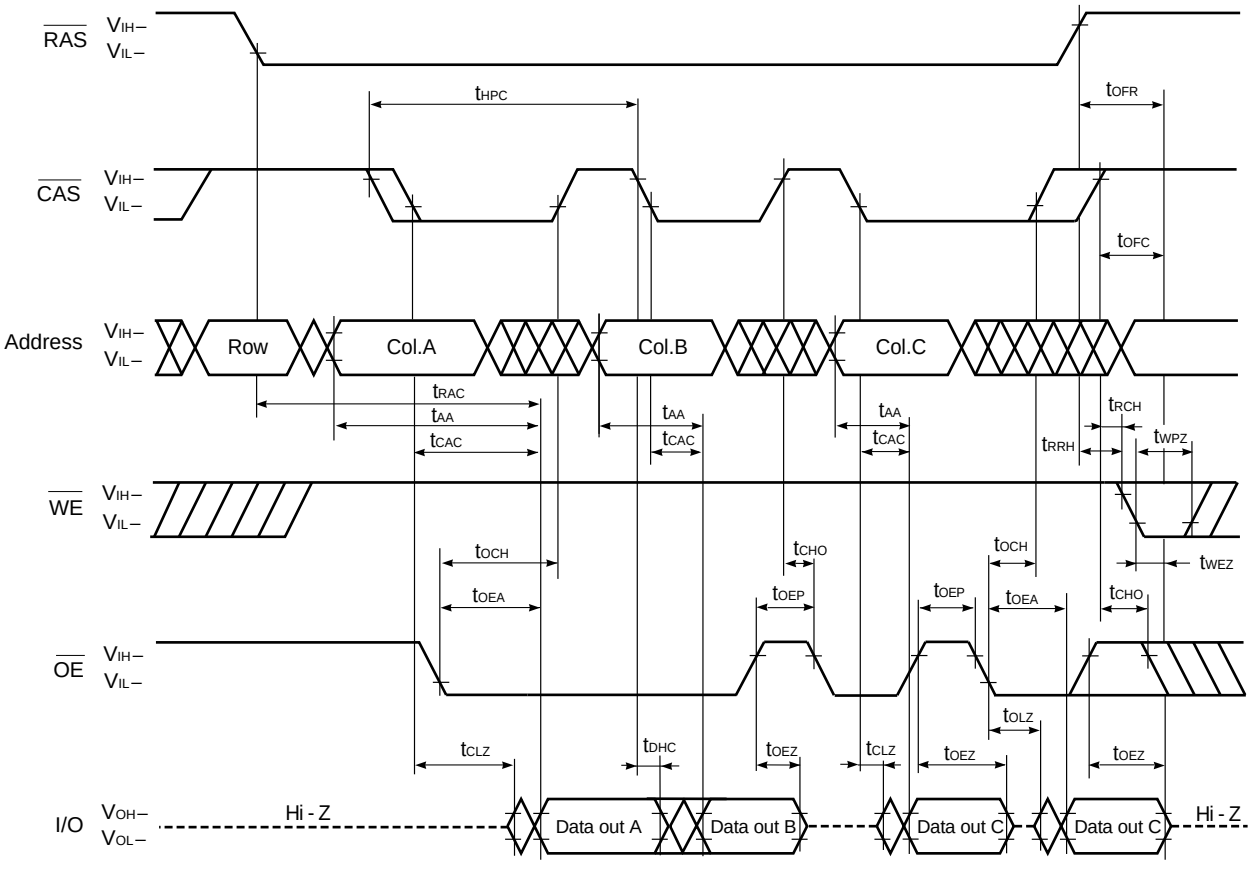
In the hyper page mode (EDO), due to the data extend function, the $\overline{CAS}$ cycle time can be shorter than in the fast page mode if the timing margin is the same.

Taking a device whose t_{RAC} is 60 ns as an example, the $\overline{CAS}$ cycle time in the fast page mode is 25 ns while that in the fast page mode is 40 ns.

In the hyper page mode (EDO), read (data out) and write (data in) cycles can be executed repeatedly during one $\overline{RAS}$ cycle. The hyper page mode (EDO) allows both read and write operations during one cycle.

The following shows a part of the hyper page mode (EDO) read cycle. Specifications to be observed are described in the next page.

Hyper Page Mode (EDO) Read Cycle



Cautions when using the hyper page mode (EDO)

1. $\overline{CAS}$ access should be used to operate t_{HPC} at the MIN. value.

2. To make I/Os to Hi-Z in read cycle, it is necessary to control $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$ as follows. The effective specification depends on the state of each signal.

(1) Both $\overline{RAS}$ and $\overline{CAS}$ are inactive (at the end of read cycle)
$\overline{WE}$: inactive, $\overline{OE}$: active
t_{OFC} is effective when $\overline{RAS}$ is inactivated before $\overline{CAS}$ is inactivated.
t_{OFR} is effective when $\overline{CAS}$ is inactivated before $\overline{RAS}$ is inactivated.
The slower of t_{OFC} and t_{OFR} becomes effective.

(2) Both $\overline{RAS}$ and $\overline{CAS}$ are active or either $\overline{RAS}$ or $\overline{CAS}$ is active (in read cycle)
$\overline{WE}$, $\overline{OE}$: inactive ····· t_{OEZ} is effective.
Both $\overline{RAS}$ and $\overline{CAS}$ are inactive or $\overline{RAS}$ is active and $\overline{CAS}$ is inactive (at the end of read cycle)
$\overline{WE}$, $\overline{OE}$: active and either t_{RRH} or t_{RCH} must be met ····· t_{WEZ} and t_{WPZ} are effective.
The faster of t_{OEZ} and t_{WEZ} becomes effective.

The faster of (1) and (2) becomes effective.

3. In read cycle, the effective specification depends on the state of $\overline{CAS}$ signal when controlling data output with the $\overline{OE}$ signal.

(1) $\overline{CAS}$: inactive, $\overline{OE}$: active ····· t_{OHO} is effective.

(2) $\overline{CAS}$, $\overline{OE}$: active ····· t_{OCH} is effective.

Electrical Specifications

- All voltages are referenced to GND.
- After power up ($V_{CC} \geq V_{CC\ (MIN.)}$), wait more than 100 μs ($\overline{RAS}$, $\overline{CAS}$ inactive) and then, execute eight $\overline{CAS}$ before $\overline{RAS}$ or $\overline{RAS}$ only refresh cycles as dummy cycles to initialize internal circuit.

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Voltage on any pin relative to GND	V_T		–1.0 to +7.0	V
Supply voltage	V_{CC}		–1.0 to +7.0	V
Output current	I_O		50	mA
Power dissipation	P_D		1	W
Operating ambient temperature	T_A		0 to +70	°C
Storage temperature	T_{stg}		–55 to +125	°C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V_{CC}		4.5	5.0	5.5	V
High level input voltage	V_{IH}		2.4		V_{CC} + 1.0	V
Low level input voltage	V_{IL}		–1.0		+0.8	V
Operating ambient temperature	T_A		0		70	°C

Capacitance (T_A = 25 °C, f = 1 MHz)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{I1}	Address			5	pF
	C_{I2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$			7	
Data input/output capacitance	$C_{I/O}$	I/O			7	pF

★ **DC Characteristics (Recommended operating conditions unless otherwise noted)**

Parameter	Symbol	Test condition		MIN.	MAX.	Unit	Notes
Operating current	I_{CC1}	$\overline{RAS}$, $\overline{CAS}$ cycling $t_{RC} = t_{RC\ (MIN.)}$, I_O = 0 mA	t_{RAC} = 60 ns		110	mA	1, 2, 3
			t_{RAC} = 70 ns		100		
Standby current	I_{CC2}	$\overline{RAS}$, $\overline{CAS} \geq V_{IH\ (MIN.)}$, I_O = 0 mA			2.0	mA	
		$\overline{RAS}$, $\overline{CAS} \geq V_{CC}$ – 0.2 V, I_O = 0 mA			1.0		
$\overline{RAS}$ only refresh current	I_{CC3}	$\overline{RAS}$ cycling, $\overline{CAS} \geq V_{IH\ (MIN.)}$ $t_{RC} = t_{RC\ (MIN.)}$, I_O = 0 mA	t_{RAC} = 60 ns		110	mA	1, 2, 3 ,4
			t_{RAC} = 70 ns		100		
Operating current (Hyper page mode (EDO))	I_{CC4}	$\overline{RAS} \leq V_{IL\ (MAX.)}$, $\overline{CAS}$ cycling $t_{HPC} = t_{HPC\ (MIN.)}$, I_O = 0 mA	t_{HPC} = 25 ns		100	mA	1, 2, 5
			t_{HPC} = 30 ns		90		
			t_{HPC} = 35 ns		80		
$\overline{CAS}$ before $\overline{RAS}$ refresh current	I_{CC5}	$\overline{RAS}$ cycling $t_{RC} = t_{RC\ (MIN.)}$, I_O = 0 mA	t_{RAC} = 60 ns		110	mA	1, 2
			t_{RAC} = 70 ns		100		
Input leakage current	$I_{I\ (L)}$	V_I = 0 to 5.5 V All other pins not under test = 0 V		–10	+10	μA	
Output leakage current	$I_{O\ (L)}$	V_O = 0 to 5.5 V Output is disabled (Hi-Z)		–10	+10	μA	
High level output voltage	V_{OH}	I_O = –2.5 mA		2.4		V	
Low level output voltage	V_{OL}	I_O = +2.1 mA			0.4	V	

Notes 1. I_{CC1}, I_{CC3}, I_{CC4} and I_{CC5} depend on cycle rates (t_{RC} and t_{HPC}).

2. Specified values are obtained with outputs unloaded.

3. I_{CC1} and I_{CC3} are measured assuming that address can be changed once or less during $\overline{RAS} \leq V_{IL\ (MAX.)}$ and $\overline{CAS} \geq V_{IH\ (MIN.)}$.

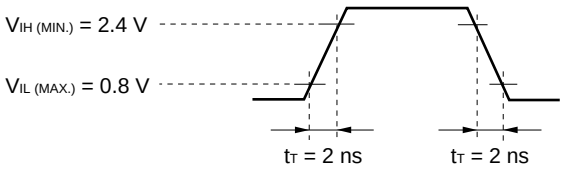
4. I_{CC3} is measured assuming that all column address inputs are held at either high or low.

5. I_{CC4} is measured assuming that all column address inputs are switched only once during each hyper page (EDO) cycle.

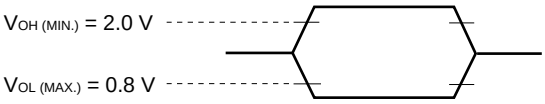
★ AC Characteristics (Recommended Operating Conditions unless otherwise noted)

AC Characteristics Test Conditions

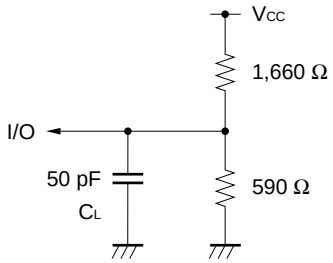
(1) Input timing specification



(2) Output timing specification



(3) Output load condition



Common to Read, Write, Read Modify Write Cycle

Parameter	Symbol	t_{HPC} = 25 ns		t_{HPC} = 30 ns		t_{HPC} = 35 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read / Write cycle time	t_{RC}	109	–	124	–	124	–	ns	
$\overline{RAS}$ precharge time	t_{RP}	45	–	50	–	50	–	ns	
$\overline{CAS}$ precharge time	t_{CPN}	10	–	10	–	10	–	ns	
$\overline{RAS}$ pulse width	t_{RAS}	60	10,000	70	10,000	70	10,000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	10	10,000	12	10,000	15	10,000	ns	
$\overline{RAS}$ hold time	t_{RSH}	17	–	20	–	20	–	ns	
$\overline{CAS}$ hold time	t_{CSH}	50	–	60	–	70	–	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	20	43	20	50	20	50	ns	1
$\overline{RAS}$ to column address delay time	t_{RAD}	15	30	15	35	15	30	ns	1
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	5	–	5	–	5	–	ns	2
Row address setup time	t_{ASR}	0	–	0	–	0	–	ns	
Row address hold time	t_{RAH}	10	–	10	–	10	–	ns	
Column address setup time	t_{ASC}	0	–	0	–	0	–	ns	
Column address hold time	t_{CAH}	10	–	12	–	15	–	ns	
$\overline{OE}$ lead time referenced to $\overline{RAS}$	t_{OES}	0	–	0	–	0	–	ns	
$\overline{CAS}$ to data setup time	t_{CLZ}	0	–	0	–	0	–	ns	
$\overline{OE}$ to data setup time	t_{OLZ}	0	–	0	–	0	–	ns	
$\overline{OE}$ to data delay time	t_{OED}	15	–	15	–	15	–	ns	
Transition time (rise and fall)	t_T	2	50	2	50	2	50	ns	
Refresh time	t_{REF}	–	8	–	8	–	8	ms	

Notes 1. For read cycles, access time is defined as follows:

Input conditions	Access time	Access time from $\overline{RAS}$
$t_{RAD} \leq t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{RAC\ (MAX.)}$	$t_{RAC\ (MAX.)}$
$t_{RAD} > t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{AA\ (MAX.)}$	$t_{RAD} + t_{AA\ (MAX.)}$
$t_{RCD} > t_{RCD\ (MAX.)}$	$t_{CAC\ (MAX.)}$	$t_{RCD} + t_{CAC\ (MAX.)}$

$t_{RAD\ (MAX.)}$ and $t_{RCD\ (MAX.)}$ are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC}, t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geq t_{RAD\ (MAX.)}$ and $t_{RCD} \geq t_{RCD\ (MAX.)}$ will not cause any operation problems.

2. $t_{CRP\ (MIN.)}$ requirement is applied to $\overline{RAS}$, $\overline{CAS}$ cycles.

Read Cycle

Parameter	Symbol	t_{HPC} = 25 ns		t_{HPC} = 30 ns		t_{HPC} = 35 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Access time from $\overline{RAS}$	t_{RAC}	–	60	–	70	–	70	ns	1
Access time from $\overline{CAS}$	t_{CAC}	–	17	–	20	–	20	ns	1
Access time from column address	t_{AA}	–	30	–	35	–	40	ns	1
Access time from $\overline{OE}$	t_{OEA}	–	15	–	20	–	20	ns	
Column address lead time referenced to $\overline{RAS}$	t_{RAL}	30	–	35	–	40	–	ns	
Read command setup time	t_{RCS}	0	–	0	–	0	–	ns	
Read command hold time referenced to $\overline{RAS}$	t_{RRH}	0	–	0	–	0	–	ns	2
Read command hold time referenced to $\overline{CAS}$	t_{RCH}	0	–	0	–	0	–	ns	2
Output buffer turn-off delay time from $\overline{OE}$	t_{OEZ}	0	15	0	15	0	15	ns	3
$\overline{CAS}$ hold time to $\overline{OE}$	t_{CHO}	5	–	5	–	5	–	ns	4

Notes 1. For read cycles, access time is defined as follows:

Input conditions	Access time	Access time from $\overline{RAS}$
$t_{RAD} \leq t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{RAC\ (MAX.)}$	$t_{RAC\ (MAX.)}$
$t_{RAD} > t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{AA\ (MAX.)}$	$t_{RAD} + t_{AA\ (MAX.)}$
$t_{RCD} > t_{RCD\ (MAX.)}$	$t_{CAC\ (MAX.)}$	$t_{RCD} + t_{CAC\ (MAX.)}$

$t_{RAD\ (MAX.)}$ and $t_{RCD\ (MAX.)}$ are specified as reference points only; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC}, t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geq t_{RAD\ (MAX.)}$ and $t_{RCD} \geq t_{RCD\ (MAX.)}$ will not cause any operation problems.

2. Either $t_{RCH\ (MIN.)}$ or $t_{RRH\ (MIN.)}$ should be met in read cycles.

3. $t_{OEZ(MAX.)}$ defines the time when the output achieves the condition of Hi-Z and is not referenced to V_{OH} or V_{OL}.

4. $\overline{WE}$: inactive (in read cycle)
$\overline{CAS}$: inactive, $\overline{OE}$: active ····· t_{CHO} is effective.
$\overline{CAS}$, $\overline{OE}$: active ····· t_{OCH} is effective.

Write Cycle

Parameter	Symbol	t_{HPC} = 25 ns		t_{HPC} = 30 ns		t_{HPC} = 35 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
$\overline{WE}$ hold time referenced to $\overline{CAS}$	t_{WCH}	10	–	12	–	15	–	ns	1
$\overline{WE}$ pulse width	t_{WP}	10	–	12	–	15	–	ns	1
$\overline{WE}$ lead time referenced to $\overline{RAS}$	t_{RWL}	15	–	15	–	20	–	ns	
$\overline{WE}$ lead time referenced to $\overline{CAS}$	t_{CWL}	10	–	12	–	15	–	ns	
$\overline{WE}$ setup time	t_{WCS}	0	–	0	–	0	–	ns	2
$\overline{OE}$ hold time	t_{OEH}	0	–	0	–	0	–	ns	
Data-in setup time	t_{DS}	0	–	0	–	0	–	ns	3
Data-in hold time	t_{DH}	10	–	12	–	15	–	ns	3

Notes 1. $t_{WP\ (MIN.)}$ is applied to late write cycles or read modify write cycles. In early write cycles, $t_{WCH\ (MIN.)}$ should be met.

2. If $t_{WCS} \geq t_{WCS\ (MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle.

3. $t_{DS\ (MIN.)}$ and $t_{DH\ (MIN.)}$ are referenced to the $\overline{CAS}$ falling edge in early write cycles. In late write cycles and read modify write cycles, they are referenced to the $\overline{WE}$ falling edge.

Read Modify Write Cycle

Parameter	Symbol	t_{HPC} = 25 ns		t_{HPC} = 30 ns		t_{HPC} = 35 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read modify write cycle time	t_{RWC}	145	–	160	–	165	–	ns	
$\overline{RAS}$ to $\overline{WE}$ delay time	t_{RWD}	79	–	89	–	89	–	ns	1
$\overline{CAS}$ to $\overline{WE}$ delay time	t_{CWD}	36	–	39	–	39	–	ns	1
Column address to $\overline{WE}$ delay time	t_{AWD}	49	–	54	–	59	–	ns	1

Note 1. If $t_{WCS} \geq t_{WCS\ (MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If $t_{RWD} \geq t_{RWD\ (MIN.)}$, $t_{CWD} \geq t_{CWD\ (MIN.)}$, $t_{AWD} \geq t_{AWD\ (MIN.)}$ and $t_{CPWD} \geq t_{CPWD\ (MIN.)}$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Hyper Page Mode (EDO)

Parameter	Symbol	t_{HPC} = 25 ns		t_{HPC} = 30 ns		t_{HPC} = 35 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read / Write cycle time	t_{HPC}	25	–	30	–	35	–	ns	1
$\overline{RAS}$ pulse width	t_{RASP}	60	125,000	70	125,000	70	125,000	ns	
$\overline{CAS}$ pulse width	t_{HCAS}	10	10,000	12	10,000	15	10,000	ns	
$\overline{CAS}$ precharge time	t_{CP}	10	–	10	–	10	–	ns	
Access time from $\overline{CAS}$ precharge	t_{ACP}	–	33	–	40	–	45	ns	
$\overline{CAS}$ precharge to $\overline{WE}$ delay time	t_{CPWD}	52	–	59	–	64	–	ns	2
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{RHCP}	33	–	40	–	45	–	ns	
Read modify write cycle time	t_{HPRWC}	66	–	75	–	83	–	ns	
Data output hold time	t_{DHC}	5	–	5	–	5	–	ns	
$\overline{OE}$ to $\overline{CAS}$ hold time	t_{OCH}	5	–	5	–	5	–	ns	3
$\overline{OE}$ precharge time	t_{OEP}	5	–	5	–	5	–	ns	
Output buffer turn-off delay from $\overline{WE}$	t_{WEZ}	0	15	0	15	0	15	ns	4,5
$\overline{WE}$ pulse width	t_{WPZ}	10	–	10	–	10	–	ns	5
Output buffer turn-off delay from $\overline{RAS}$	t_{OFR}	0	15	0	15	0	15	ns	4,5
Output buffer turn-off delay from $\overline{CAS}$	t_{OFC}	0	15	0	15	0	15	ns	4,5
Access time from previous $\overline{WE}$ (Hyper page mode (EDO) read and write cycle)	t_{AWE}	–	55	–	65	–	75	ns	
Access time from previous $\overline{CAS}$ (Hyper page mode (EDO) write and read cycle)	t_{ACE}	–	55	–	65	–	75	ns	

Notes 1. $t_{HPC\ (MIN.)}$ is applied to $\overline{CAS}$ access.

2. If $t_{WCS} \geq t_{WCS\ (MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If $t_{RWD} \geq t_{RWD\ (MIN.)}$, $t_{CWD} \geq t_{CWD\ (MIN.)}$, $t_{AWD} \geq t_{AWD\ (MIN.)}$ and $t_{CPWD} \geq t_{CPWD\ (MIN.)}$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

3. $\overline{WE}$: inactive (in read cycle)
$\overline{CAS}$: inactive, $\overline{OE}$: active ····· t_{OHO} is effective.
$\overline{CAS}$, $\overline{OE}$: active ····· t_{OCH} is effective.

4. $t_{OFC\ (MAX.)}$, $t_{OFR\ (MAX.)}$ and $t_{WEZ\ (MAX.)}$ define the time when the output achieves the conditions of Hi-Z and is not referenced to V_{OH} or V_{OL}.

5. To make I/Os to Hi-Z in read cycle, it is necessary to control $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$ as follows. The effective specification depends on state of each signal.

(1) Both $\overline{RAS}$ and $\overline{CAS}$ are inactive (at the end of the read cycle)
$\overline{WE}$: inactive, $\overline{OE}$: active
t_{OFC} is effective when $\overline{RAS}$ is inactivated before $\overline{CAS}$ is inactivated.
t_{OFR} is effective when $\overline{CAS}$ is inactivated before $\overline{RAS}$ is inactivated.
The slower of t_{OFC} and t_{OFR} becomes effective.

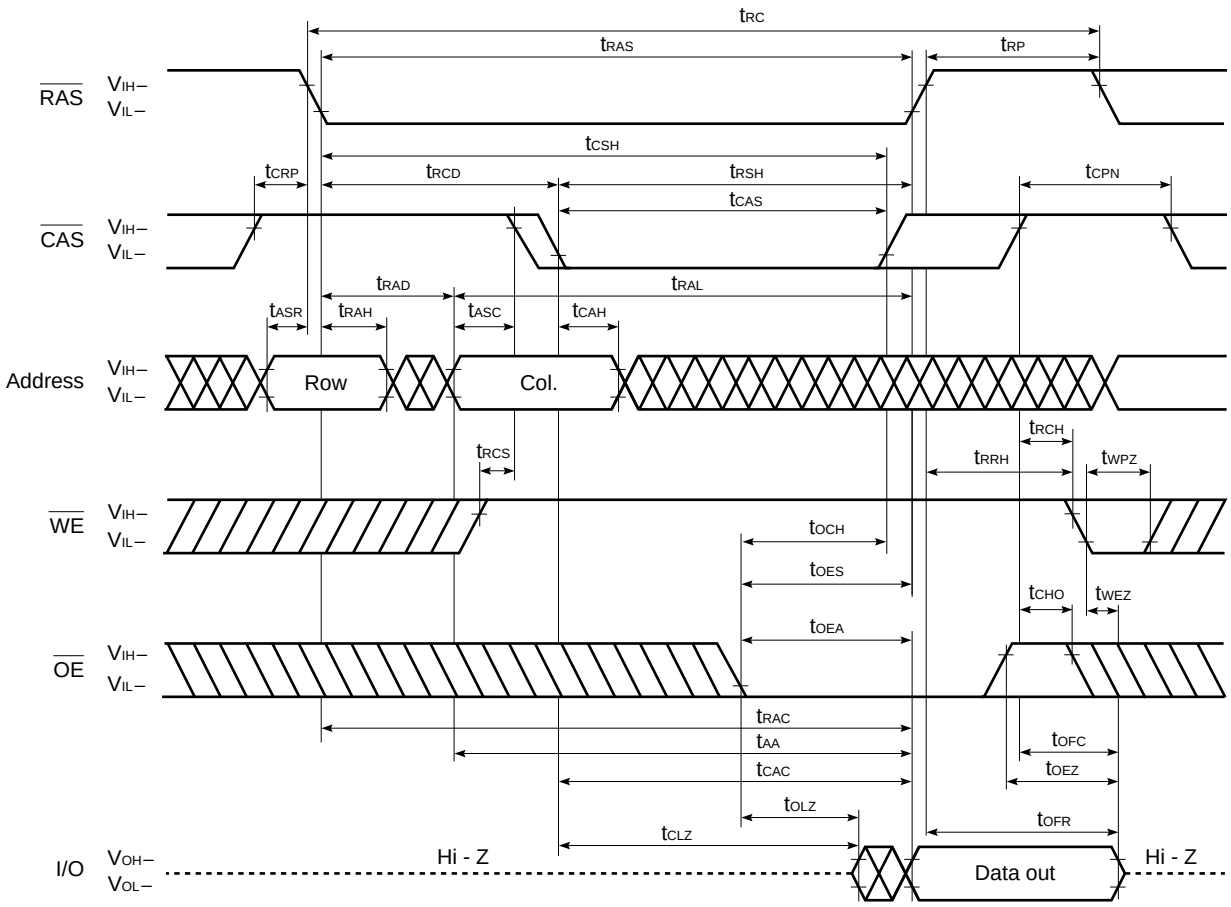
(2) Both $\overline{RAS}$ and $\overline{CAS}$ are active or either $\overline{RAS}$ or $\overline{CAS}$ is active (in read cycle)
$\overline{WE}$, $\overline{OE}$: inactive ····· t_{OEZ} is effective.
Both $\overline{RAS}$ and $\overline{CAS}$ are inactive or $\overline{RAS}$ is active and $\overline{CAS}$ is inactive (at the end of read cycle)
$\overline{WE}$, $\overline{OE}$: active and either t_{RRH} or t_{RCH} must be met ····· t_{WEZ} and t_{WPZ} are effective.
The faster of t_{OEZ} and t_{WEZ} becomes effective.

The faster of (1) and (2) becomes effective.

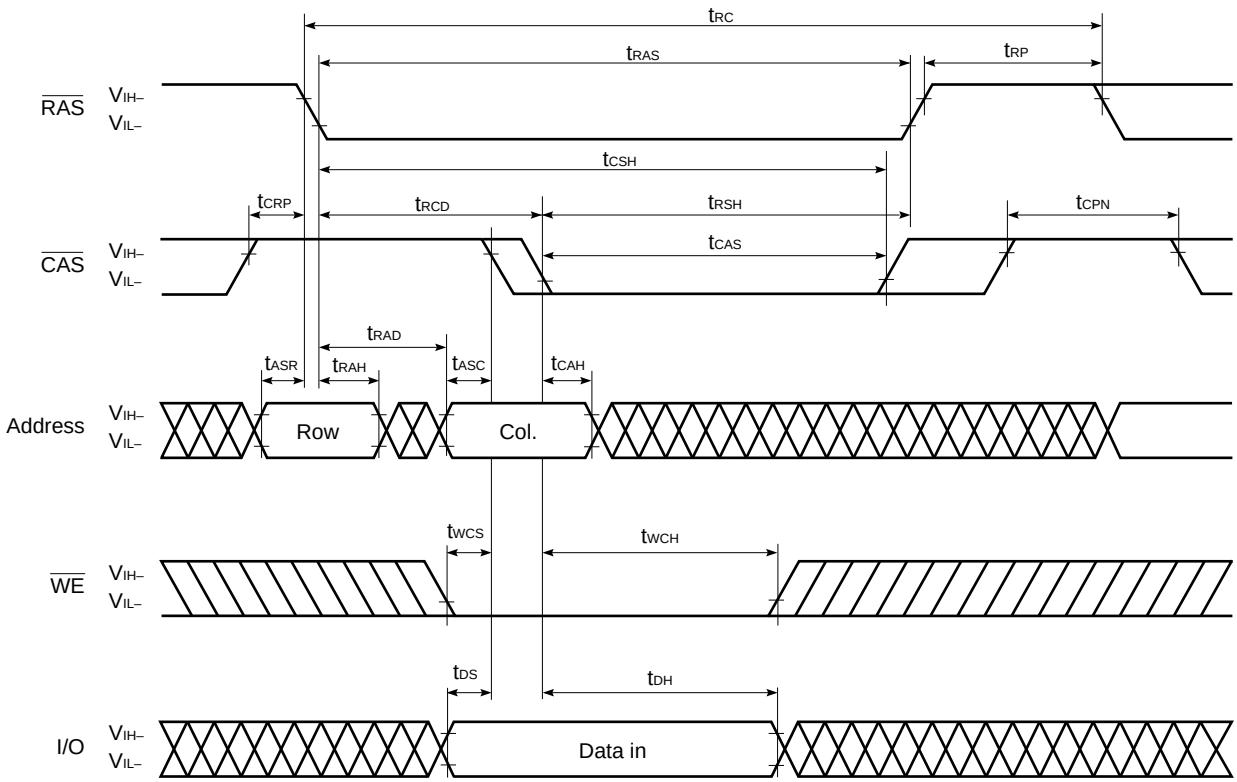
Refresh Cycle

Parameter	Symbol	t_{HPC} = 25 ns		t_{HPC} = 30 ns		t_{HPC} = 35 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
$\overline{CAS}$ setup time	t_{CSR}	5	–	5	–	5	–	ns	
$\overline{CAS}$ hold time ($\overline{CAS}$ before $\overline{RAS}$ refresh)	t_{CHR}	10	–	10	–	10	–	ns	
$\overline{RAS}$ precharge $\overline{CAS}$ hold time	t_{RPC}	5	–	5	–	5	–	ns	
$\overline{WE}$ hold time	t_{WHR}	15	–	15	–	15	–	ns	

Read Cycle

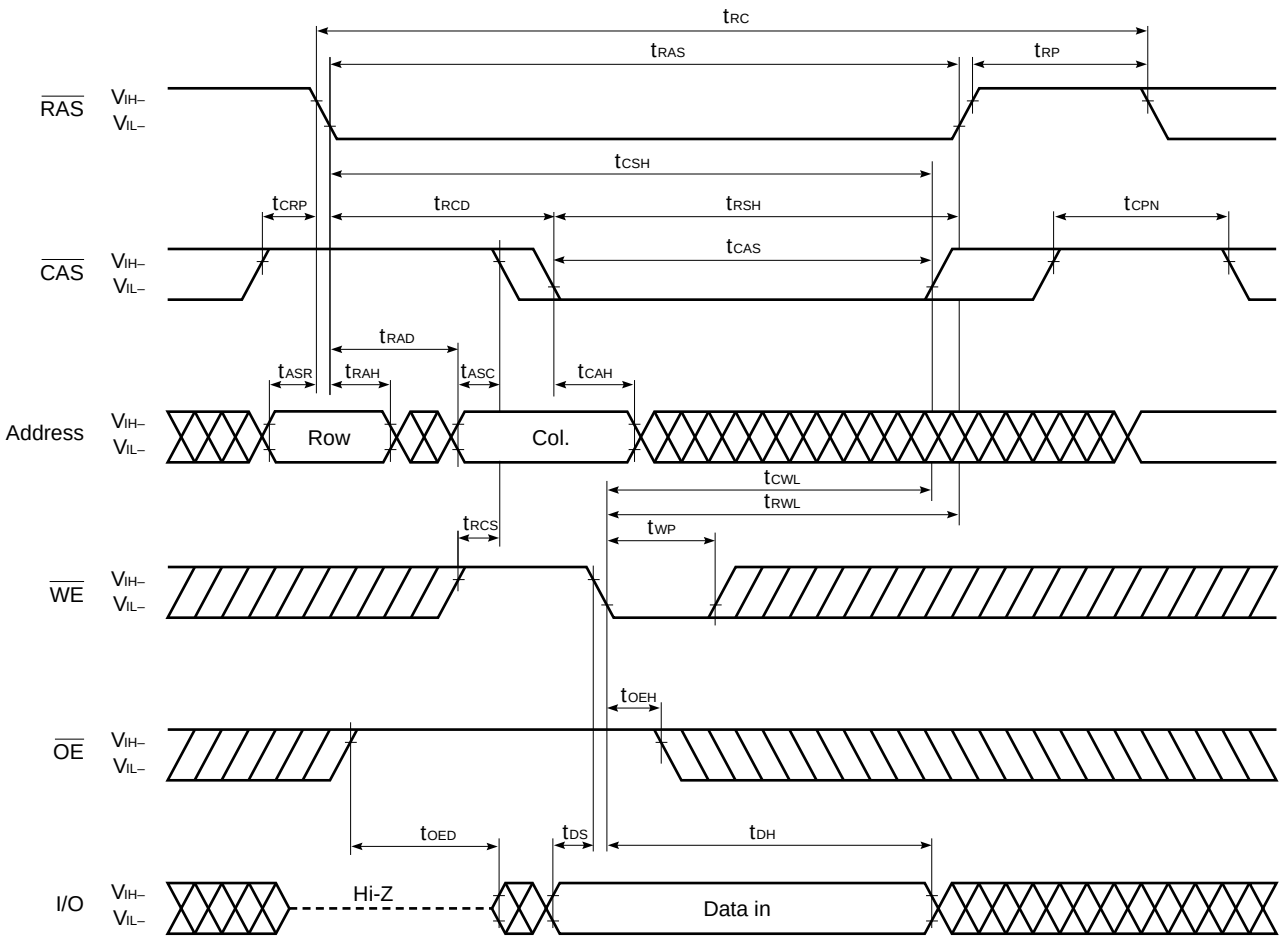

tRC
tRAS
tRP
RAS
VIH–
VIL–
tCSH
tCRP
tRCD
tRSH
tCPN
tCAS
CAS
tRAD
tRAL
tASR
tRAH
tASC
tCAH
Address
Row
Col.
tRCH
tRCS
tRRH
tWPZ
WE
tOCH
tOES
tCHO
tWEZ
tOEA
OE
tRAC
tAA
tOFC
tCAC
tOEZ
tOLZ
tOFR
tCLZ
I/O
VOH–
VOL–
Hi - Z
Data out
Hi - Z

Early Write Cycle

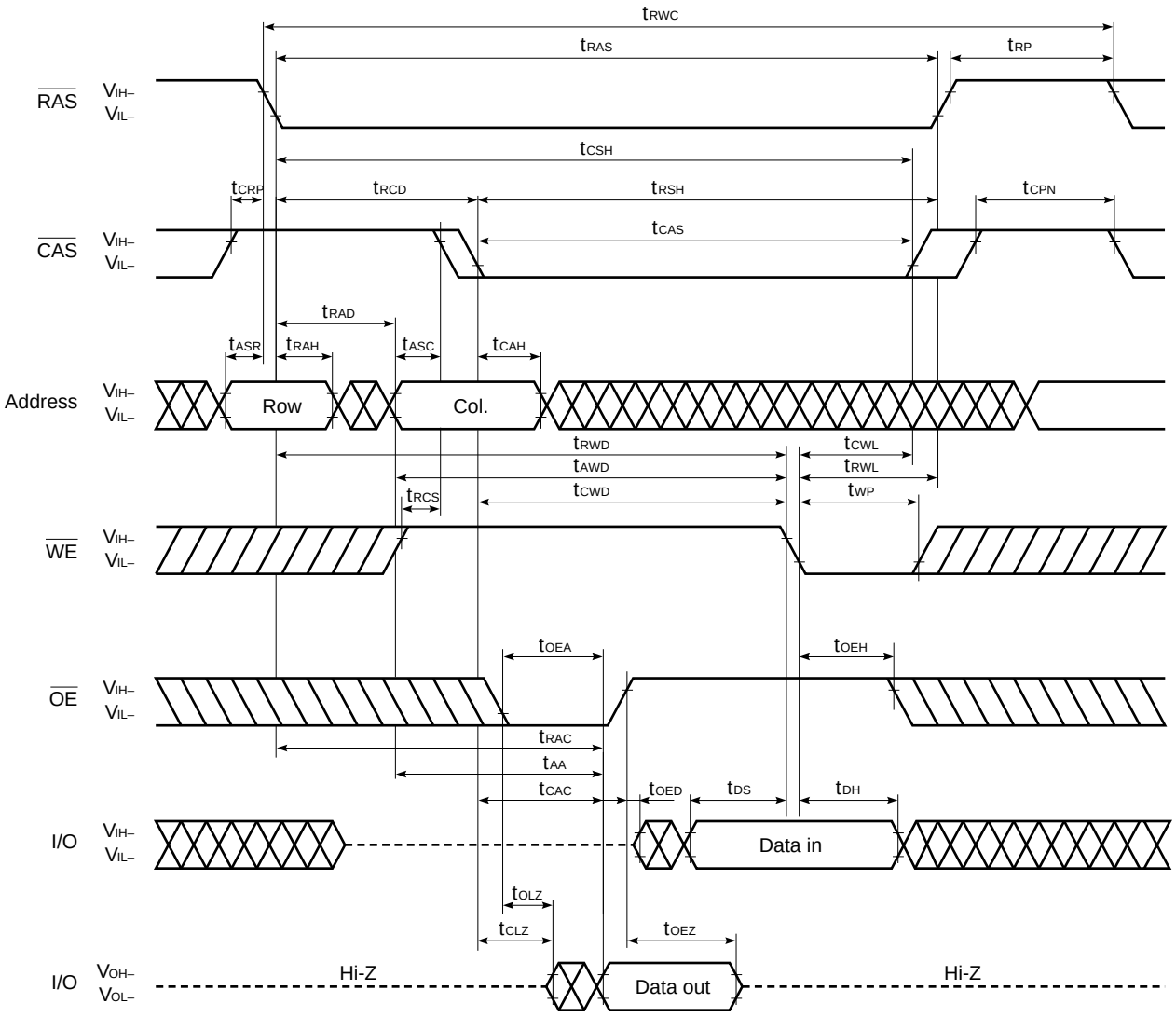


Remark $\overline{OE}$: Don't care

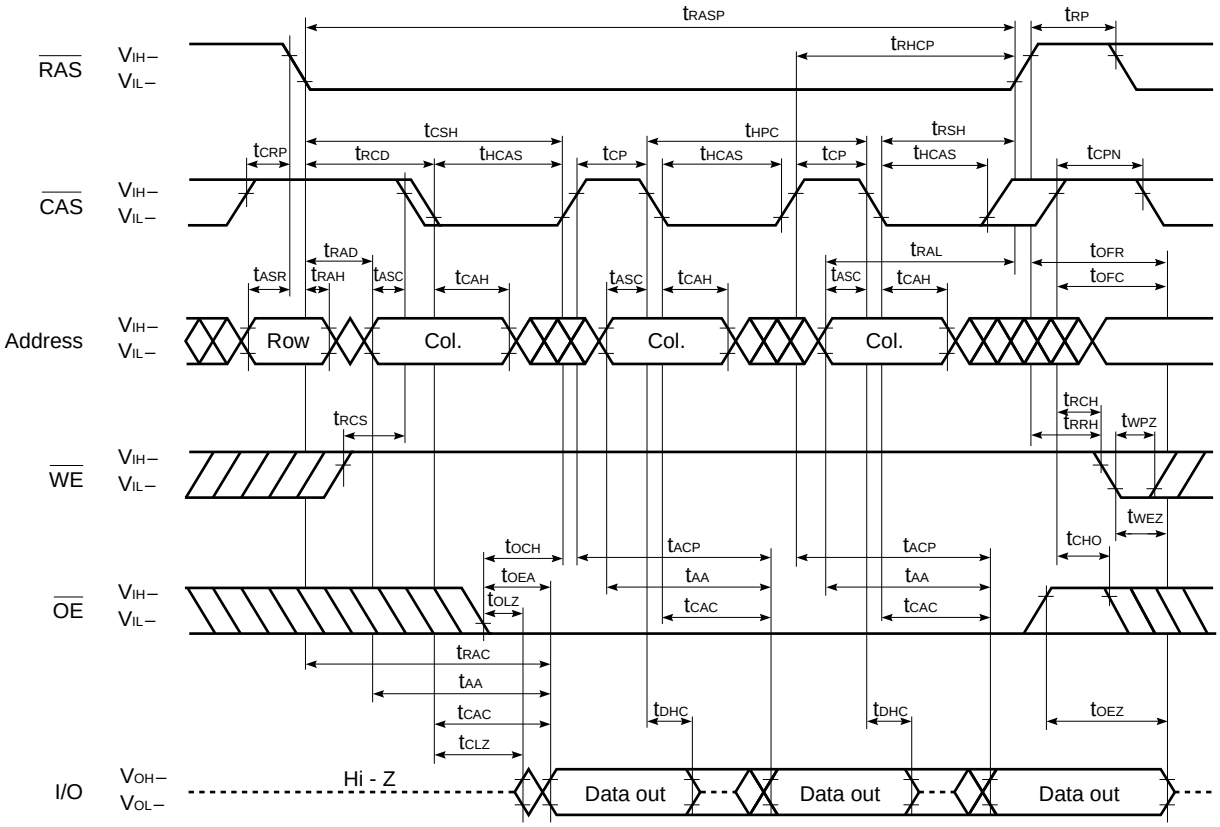
Late Write Cycle



Read Modify Write Cycle

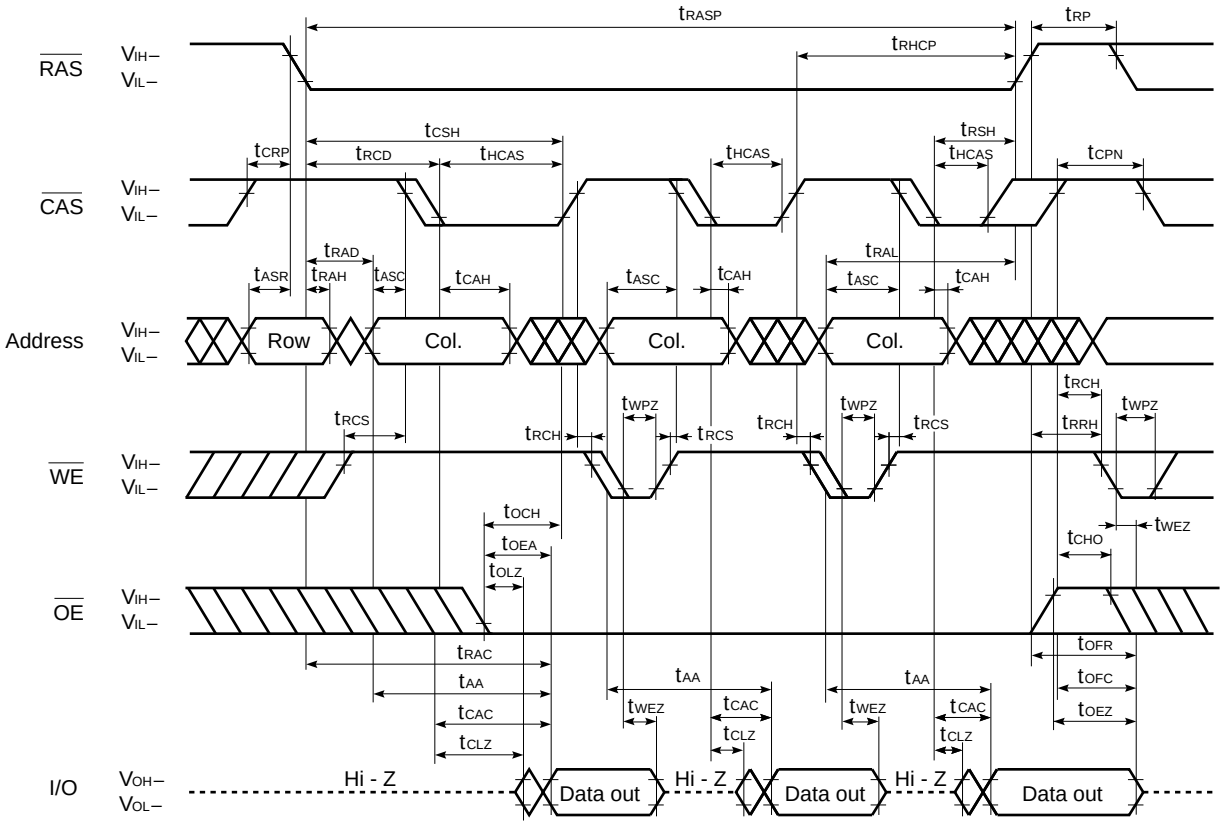


Hyper Page Mode (EDO) Read Cycle



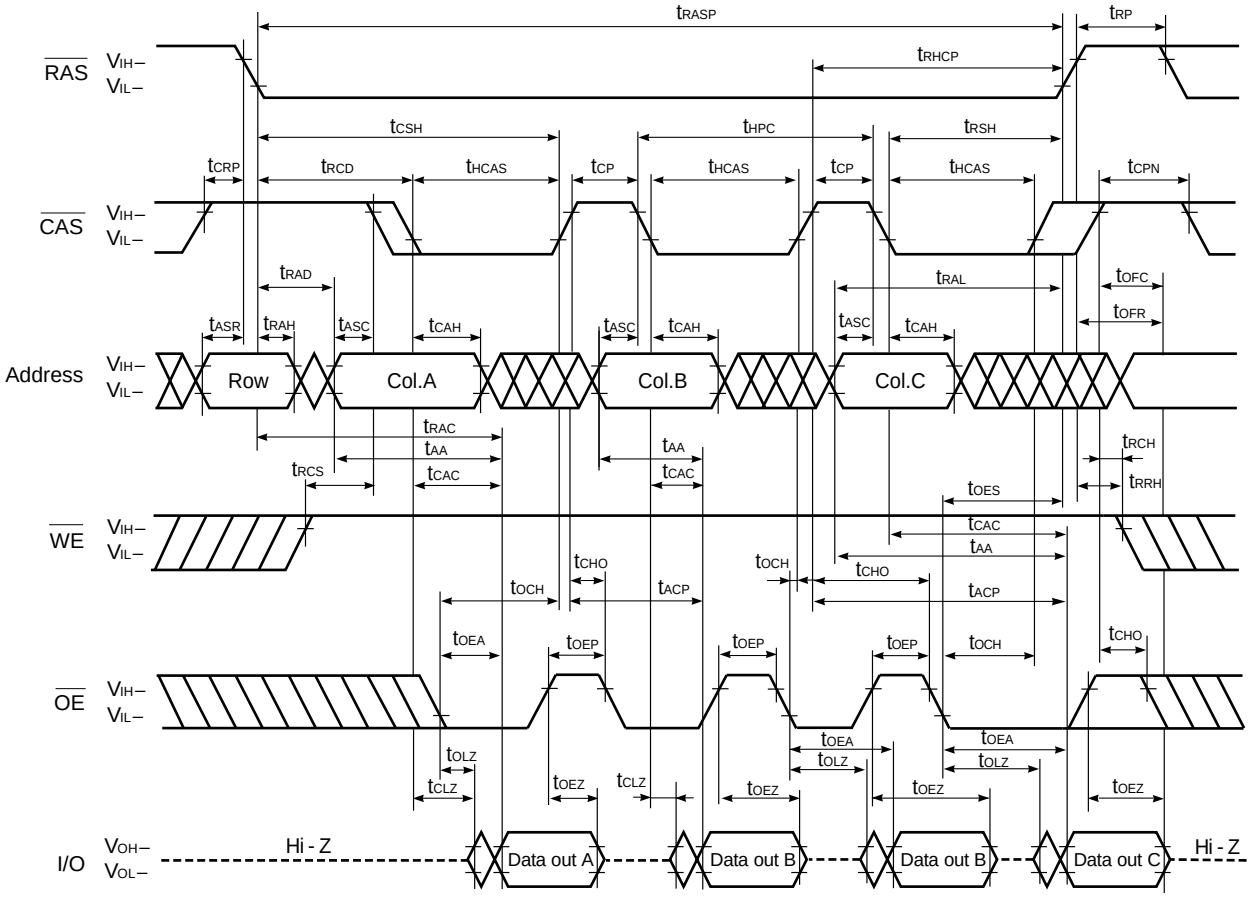
Remark In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

Hyper Page Mode (EDO) Read Cycle ($\overline{WE}$ Control)



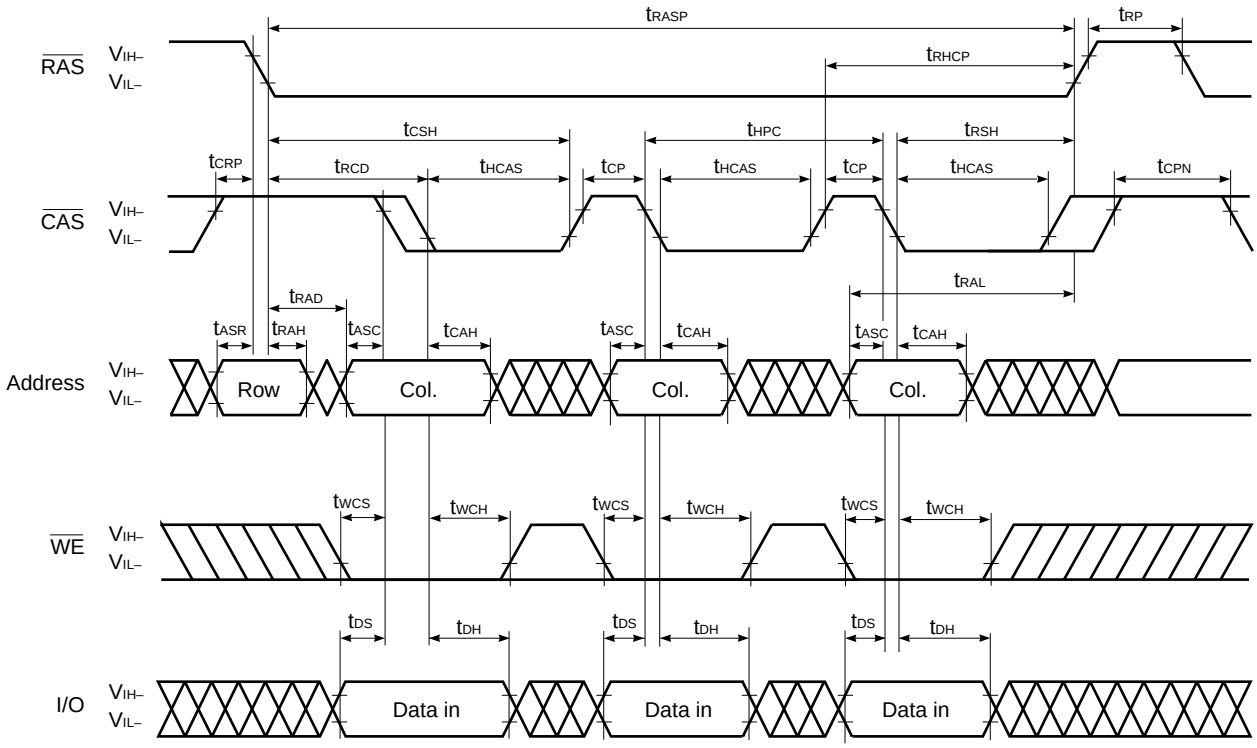
Remark In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

Hyper Page Mode (EDO) Read Cycle ($\overline{OE}$ Control)



Remark In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

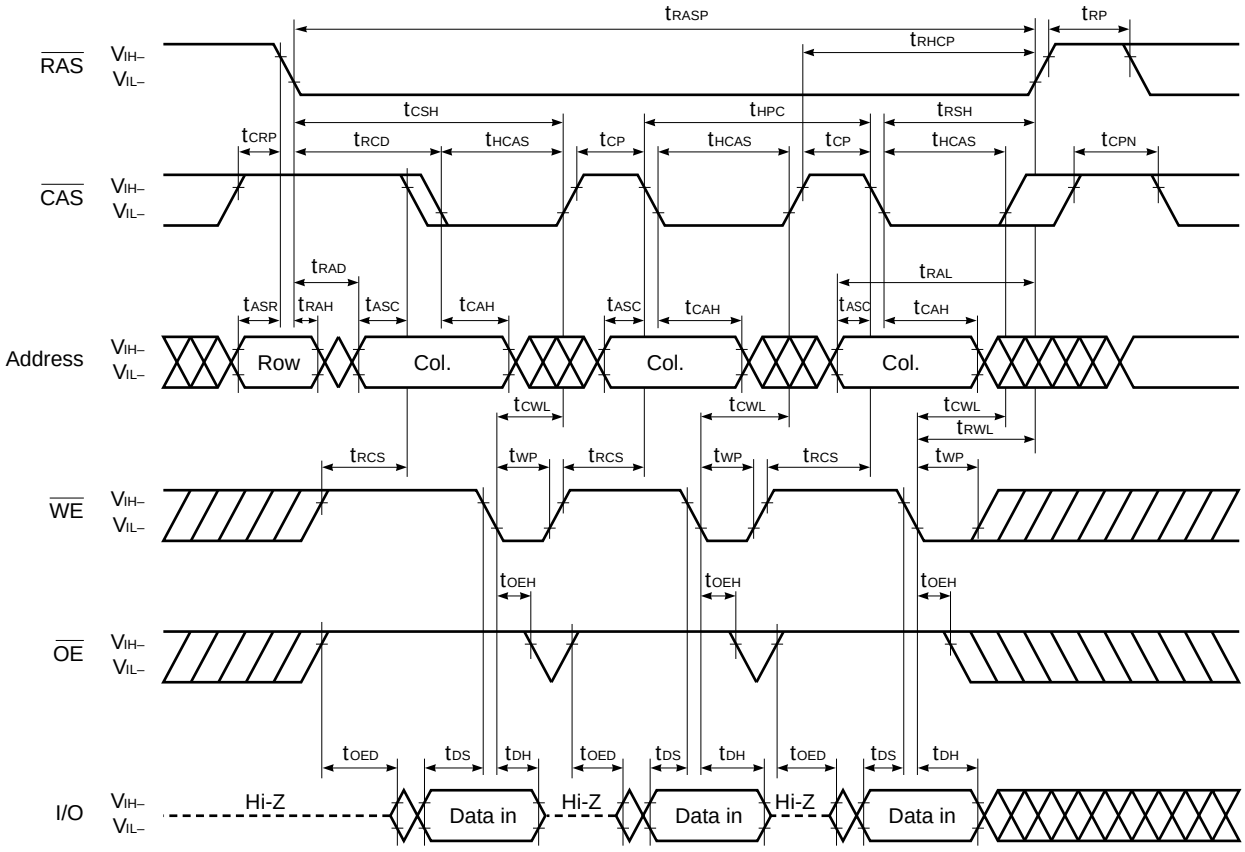
Hyper Page Mode (EDO) Early Write Cycle



Remarks 1. $\overline{OE}$: Don't care

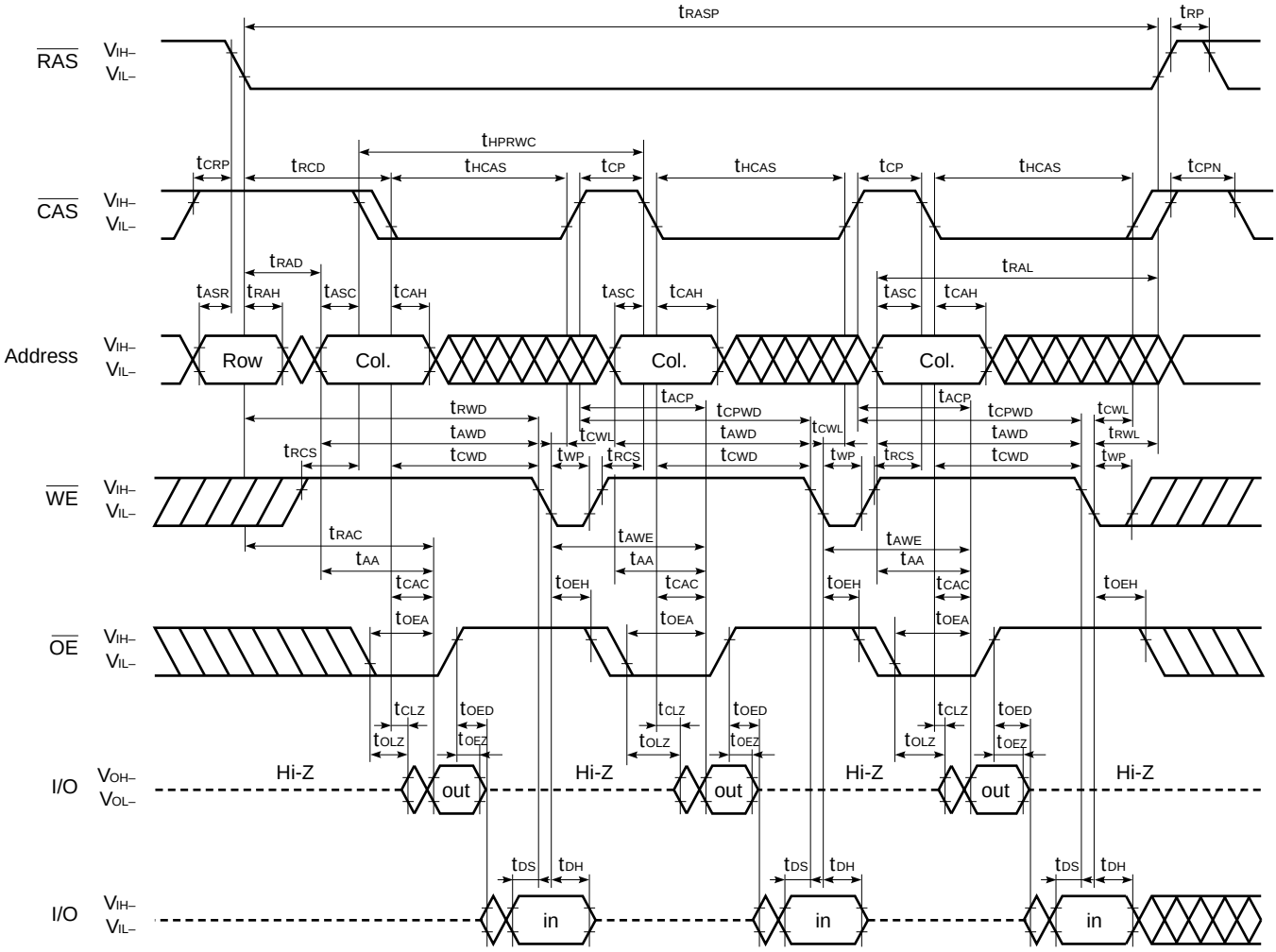
2. In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

Hyper Page Mode (EDO) Late Write Cycle



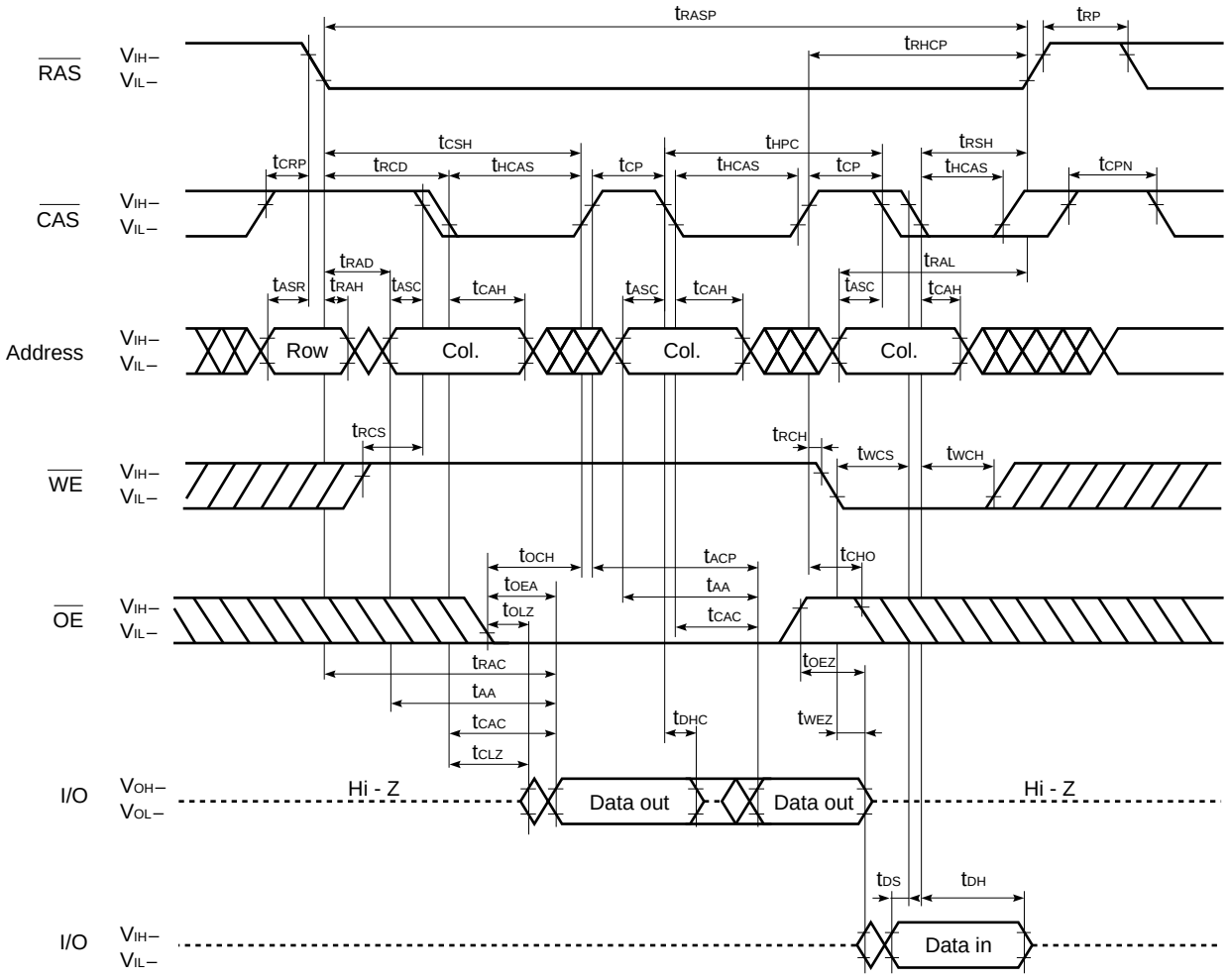
Remark In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

Hyper Page Mode (EDO) Read Modify Write Cycle



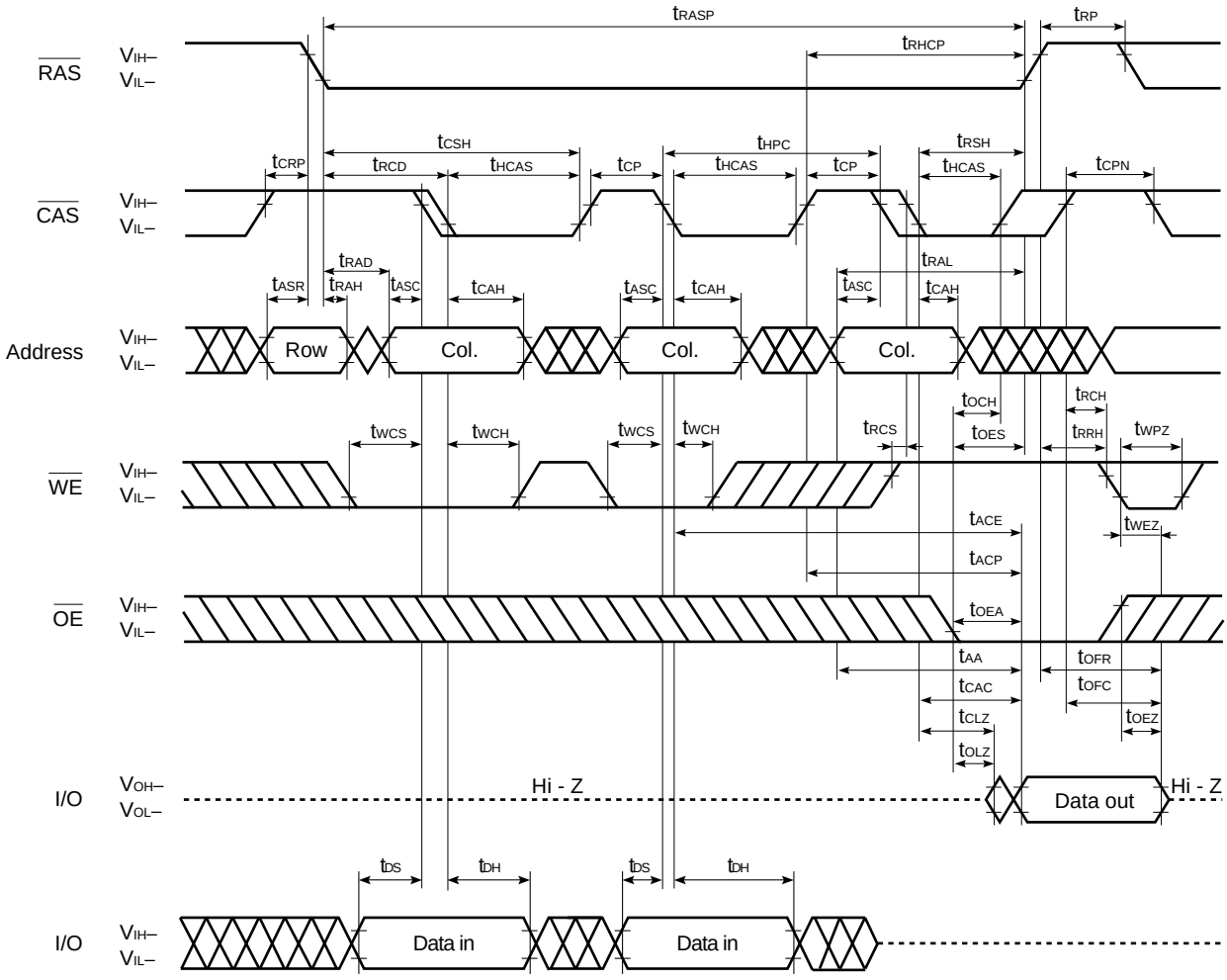
Remark In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

Hyper Page Mode (EDO) Read and Write Cycle



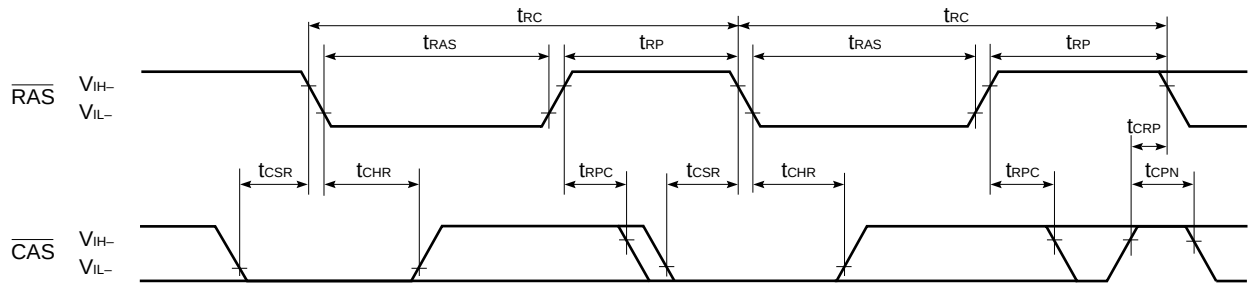
Remark In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

Hyper Page Mode (EDO) Write and Read Cycle



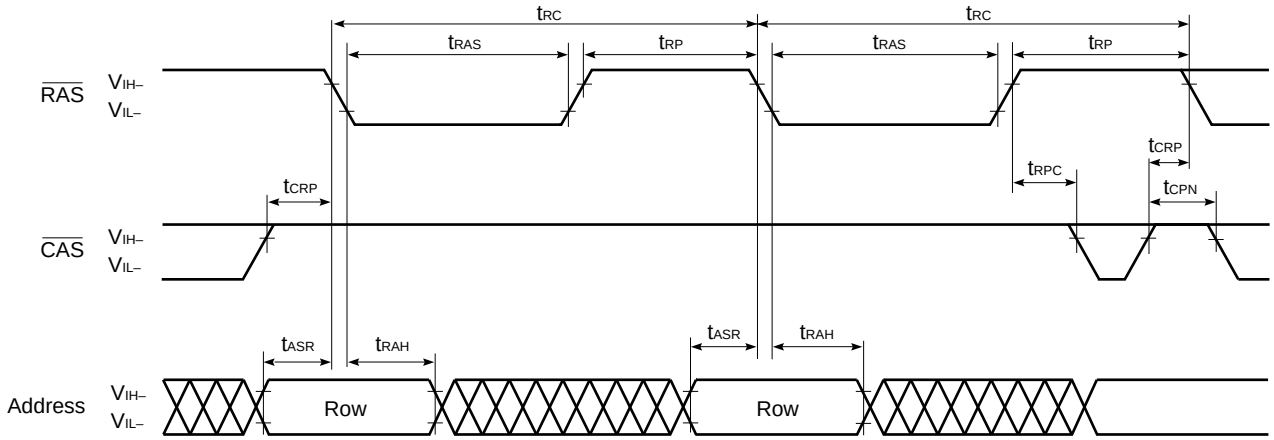
Remark In the hyper page mode (EDO), read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

$\overline{\text{CAS}}$ Before $\overline{\text{RAS}}$ Refresh Cycle



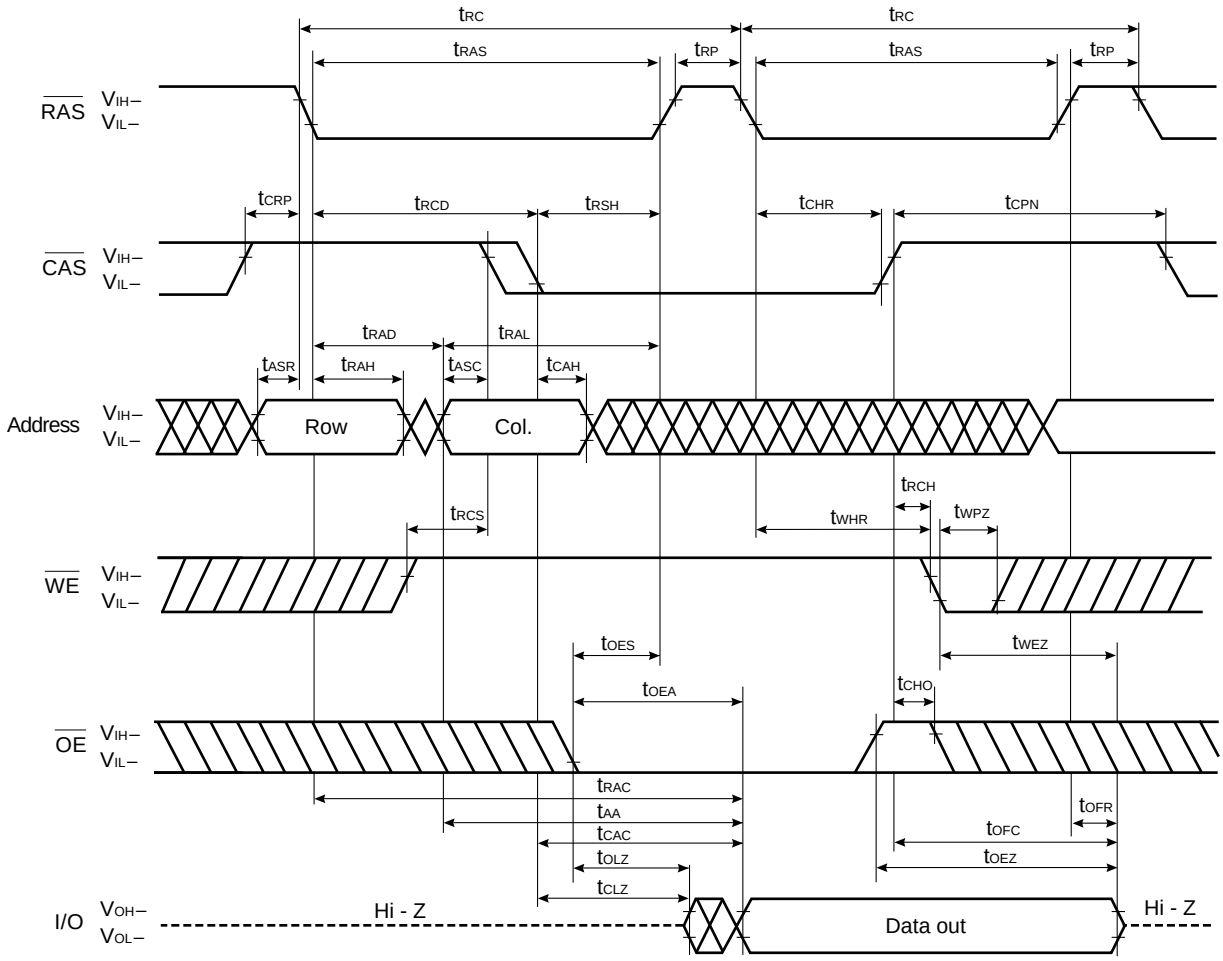
Remark Address, $\overline{\text{WE}}$, $\overline{\text{OE}}$: Don't care I/O: Hi-Z

$\overline{\text{RAS}}$ Only Refresh Cycle

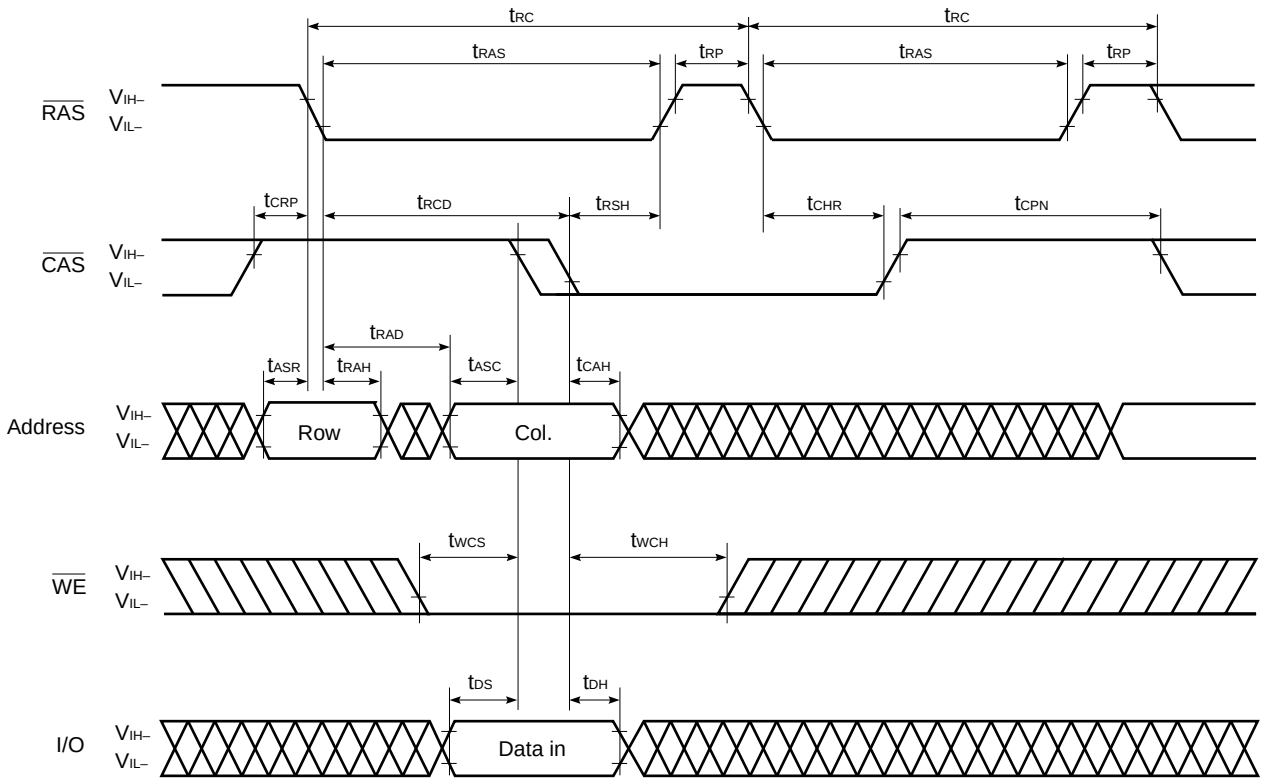


Remark $\overline{\text{WE}}$, $\overline{\text{OE}}$: Don't care I/O: Hi-Z

Hidden Refresh Cycle (Read)



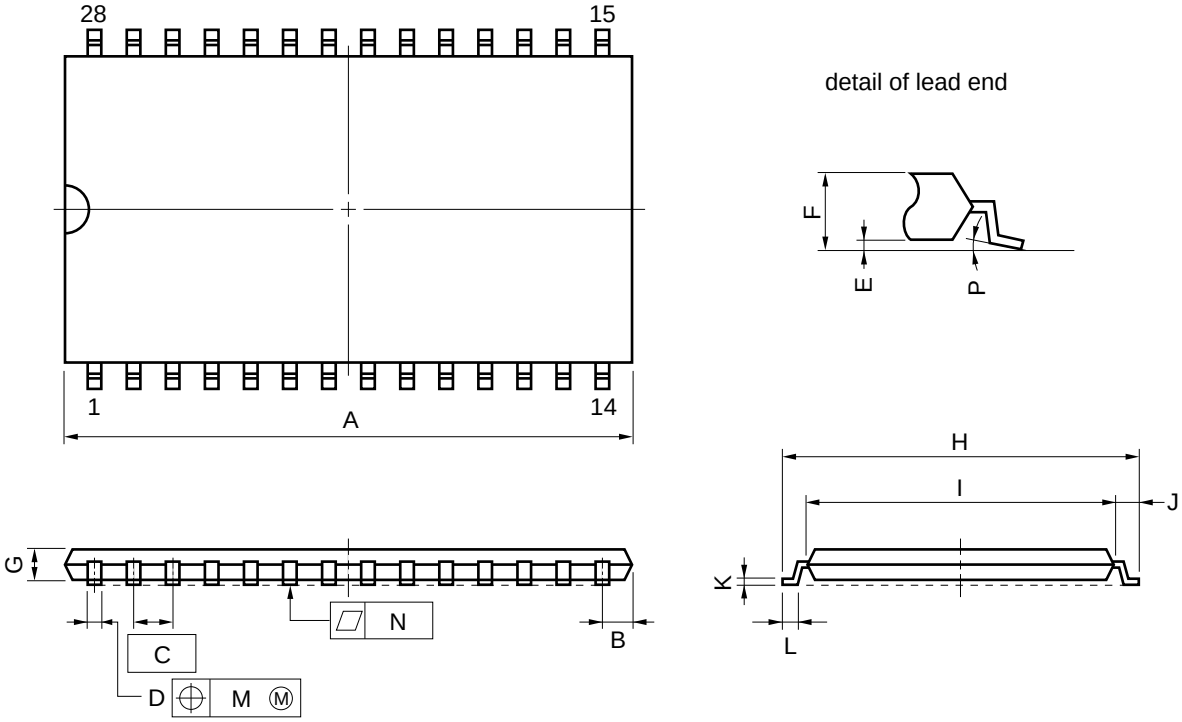
Hidden Refresh Cycle (Write)



Remark $\overline{OE}$: Don't care

Package Drawings

28 PIN PLASTIC TSOP(II) (400 mil)



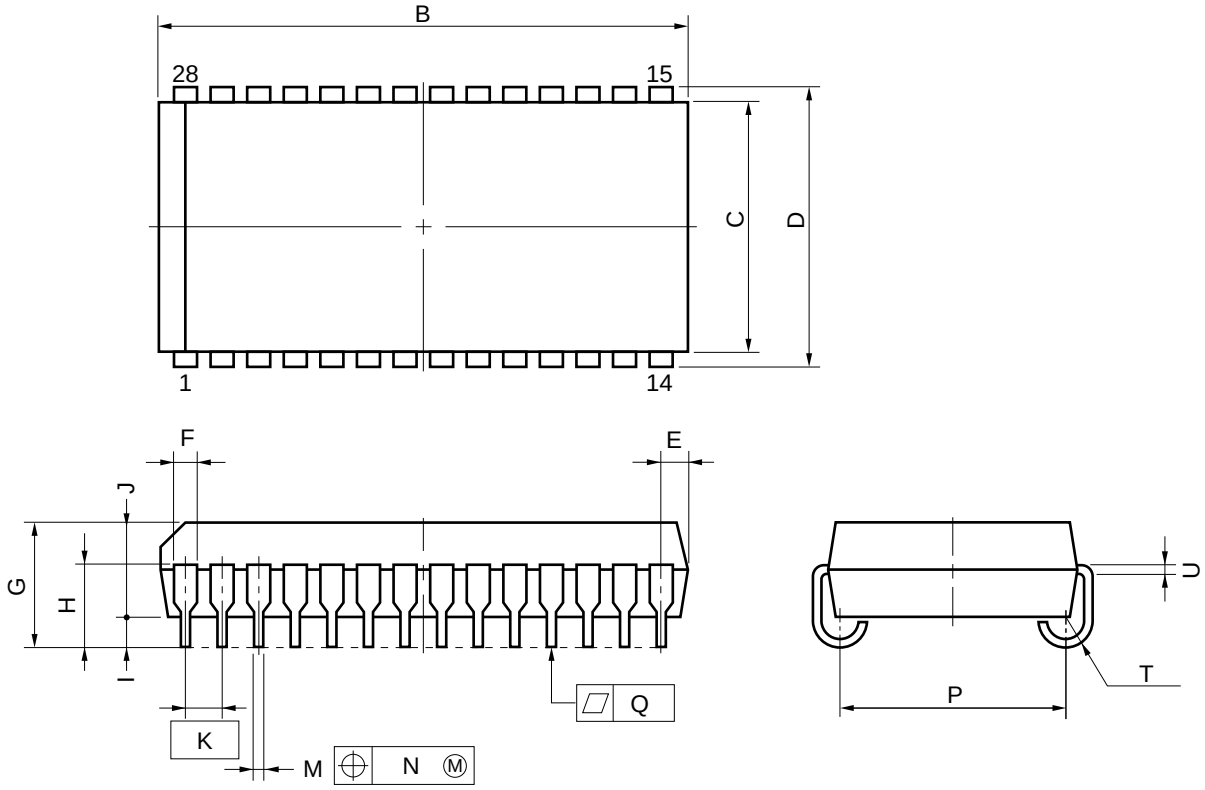
NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.63 MAX.	0.734 MAX.
B	1.075 MAX.	0.043 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.42^{+0.08}_{-0.07}$	0.017±0.003
E	0.1±0.05	0.004±0.002
F	1.2 MAX.	0.048 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	$0.031^{+0.009}_{-0.008}$
K	$0.145^{+0.025}_{-0.015}$	0.006±0.001
L	0.5±0.1	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004
P	$3^{\circ}{}^{+7^{\circ}}_{-3^{\circ}}$	$3^{\circ}{}^{+7^{\circ}}_{-3^{\circ}}$

S28G5-50-7JD5

28 PIN PLASTIC SOJ (400 mil)



NOTE
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
B	$18.67^{+0.2}_{-0.35}$	$0.735^{+0.008}_{-0.013}$
C	10.16	0.400
D	11.18±0.2	$0.440^{+0.008}_{-0.007}$
E	1.08±0.15	$0.043^{+0.006}_{-0.007}$
F	0.6	0.024
G	3.5±0.2	$0.138^{+0.008}_{-0.007}$
H	2.4±0.2	$0.094^{+0.008}_{-0.007}$
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27(T.P.)	0.050(T.P.)
M	0.40±0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.40±0.20	$0.370^{+0.008}_{-0.007}$
Q	0.15	0.006
T	R0.85	R0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

P28LA-400A-2

★ Recommended Soldering Conditions

The following conditions (see tables below and next page) must be met for soldering conditions of the μPD421805.

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (C10535E).

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

Types of Surface Mount Device

μPD421805G5-7JD: 28-pin plastic TSOP (II) (400 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface: 235 ˚C or lower, Reflow time: 30 seconds or less (210 ˚C or higher), Number of reflow processes: MAX. 3 Exposure limit: 7 days[Note] (10 hours pre-baking is required at 125 ˚C afterwards)	IR35-107-3
VPS	Peak temperature of package: 215 ˚C or lower, Reflow time: 40 seconds or less (200 ˚C or higher), Number of reflow processes: MAX. 3 Exposure limit: 7 days[Note] (10 hours pre-baking is required at 125 ˚C afterwards)	VP15-107-3
Partial heating method	Terminal temperature: 300 ˚C or lower, Time: 3 seconds or lower (Per side of the package).	———

Note Exposure limit before soldering after dry-pack package is opened.
Storage conditions: 25 ˚C and relative humidity at 65 % or less.

Caution Do not apply more than one soldering method at any one time, except for "Partial heating method".

μPD421805LE: 28-pin plastic SOJ (400 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface: 235 ˚C or lower, Reflow time: 30 seconds or less (210 ˚C or higher), Number of reflow processes: MAX. 3 Exposure limit: 7 days[Note] (20 hours pre-baking is required at 125 ˚C afterwards)	IR35-207-3
VPS	Peak temperature of package: 215 ˚C or lower, Reflow time: 40 seconds or less (200 ˚C or higher), Number of reflow processes: MAX. 3 Exposure limit: 7 days[Note] (20 hours pre-baking is required at 125 ˚C afterwards)	VP15-207-3
Partial heating method	Terminal temperature: 300 ˚C or lower, Time: 3 seconds or less (Per side of the package).	———

Note Exposure limit before soldering after dry-pack package is opened.
Storage conditions: 25 ˚C and relative humidity at 65 % or less.

Caution Do not apply more than one soldering method at any one time, except for "Partial heating method".

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note: Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note: No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS device behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note: Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

[MEMO]